Amendments to the Specification:

Please replace the paragraph beginning on page 7, line 4, with the following amended paragraph:

-- As shown in FIGs. 2 and 3, ~~Heat~~ heat-dissipation stud 120 may be relatively cylindrical in shape, and then formed to fit the circuit at one end, as in ~~FIG~~ FIG. 2 or having a relatively square or rectangular cross-section to align more closely with the shape of the circuit device ~~15~~ 150, as in ~~FIG~~ FIG. 3. It will be appreciated that the device 150 is attached to the stud 120 having similar expansion. Accrodingly, heat is moved away from the device 150, whicle the thermal stresses are along the surface area 130 between the stud 120 and the base 110, rather than in the planes parallel to the device 150 and the stud. In this way, the selection of base material may be done on a best match of CTE(s) of all the circuit and adjacent elements. Since the base is substantially removed from the heat path, its thermal conductivity is not a primary concern. The stud 120 and base 110 composite heat sink rovides thermal transport perpendicular to the die and minimal thermal stresses parallel to the die. --

Please replace the paragraph beginning on page 9, line 9, with the following amended paragraph:

-- FIG. 7 illustrates a flow chart for manufacturing a heat-dissipating device according to the present invention. On or more heat-dissipating studs 120, 220, 222, 320, 420~~, 520~~ may be chosen or formed 710 by means of stamping, machining, etching or laser cutting from any known heat sink material, alloy or combination thereof, such as copper, tungsten, molybdenum, aluminum, copper/molybdenum/copper or other known heat sink material. It should be noted that the material of the stud may be selected for CTE matching with the device to be cooled 150, 250, 252, 350, 450~~, 550~~. One or more heat-dissipating bases 110, 210, 310, 410~~, 510~~ is selected or formed 720 from any known heat sink material, alloy or combination thereof, such as Aluminum Silicon Carbide, Copper, Aluminum, carbon/metal composite, ceramic, CuW, tungsten, aluminum carbide, silicon carbide or other commonly known heat sink material with a lower CTE. The stud may be

inserted into the base by pressing or casting or other known method 730. Alternatively, the aperture may be fored by machining, stamping or other known means and the stud may be inserted and mated therein by pressing, bonding, soldering brazing, soldering, adheiseve bonding, idffusino bonding, cold diffusion under high pressure, a thermally conductive metallic adheisvev or other known attachment means 730. One or more heat-dissipating devices 100, 200, 300, 400~~, 500~~ may be fored 740 by conducting steps 710-730 on a large billet and then machining, cutting, etching or using other known separation means to create individual heat-dissipating devices 100, 200, 300, 400~~, 500~~ without the necessity of step 740. --